

G 1 2 3 4 5 6 7 8 9

A

B

C

D

E

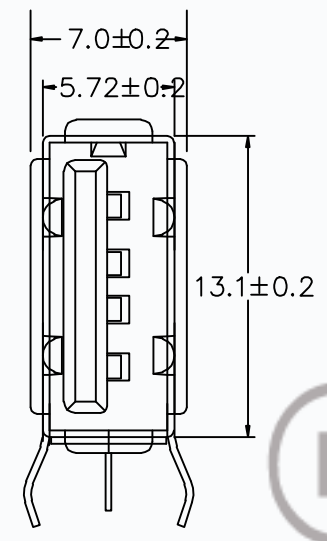
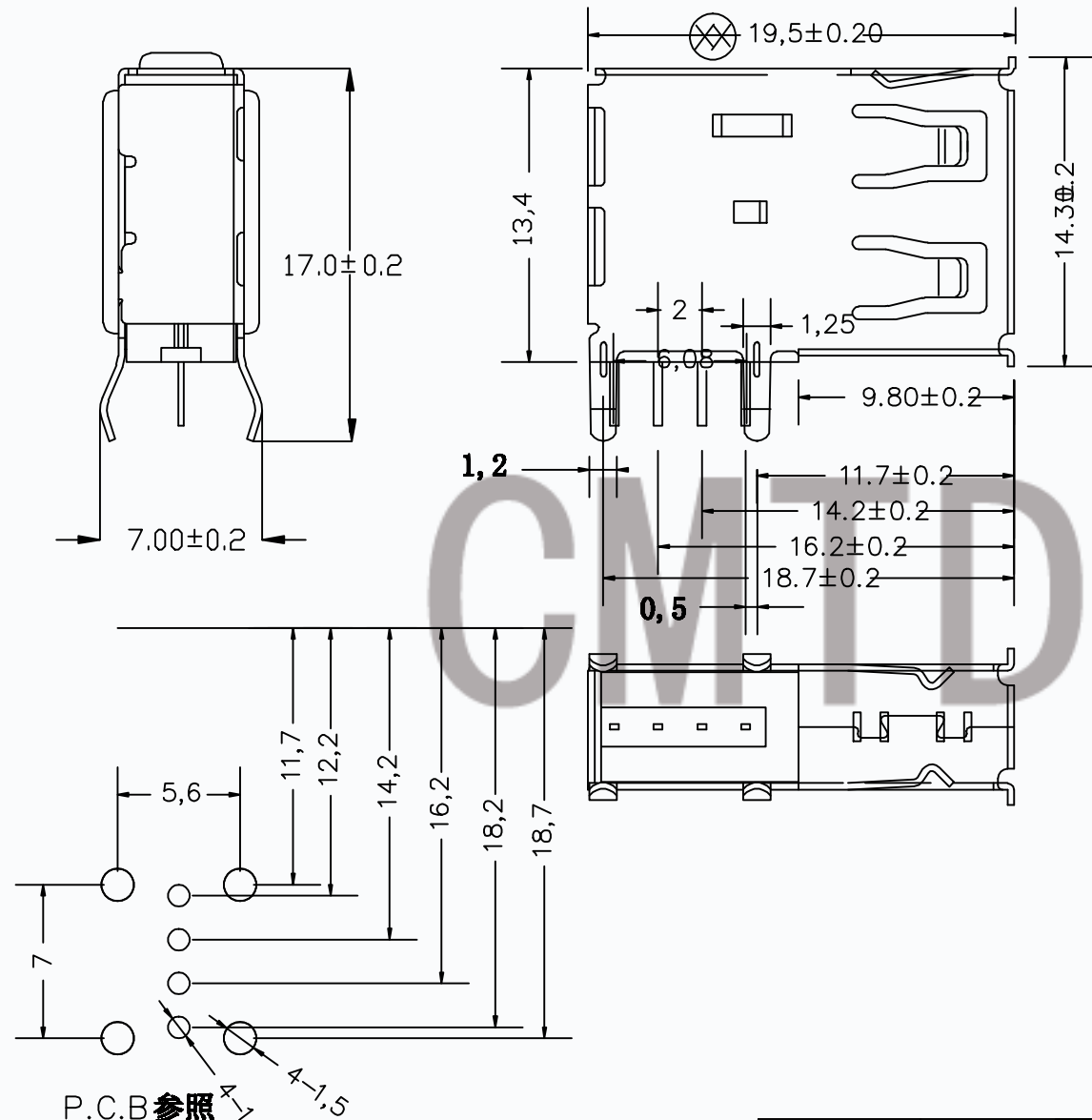
A

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NOTES:

1. MATERIAL SPECIFICATION
 - 1) INSULATION MATERIAL THERMOPLASTIC.
 - 2) SHELL: COPPER ALLOY/SPCC, T: 0.30mm
PLATING: NICKEL
 - 3) TERMINAL: COPPER ALLOY, T: 0.25mm
PLATING: GOLD/TIN PLATED.
 2. ELECTRICAL CHARACTERISTIC:
 - 1) INSULATION RESISTANCE: 1000MΩ MIN.
 - 2) CONTACT RESISTANCE: 30mΩ MAX.
 - 3) WITHSTANDING VOLTAGE: 500V AC.
 3. MECHANICAL CHARACTERISTICS:
 - 1) INSERTION FORCE: 3.57Kgf MAX.
 - 2) EXTRACTION FORCE: 1.02Kgf MIN.
- ORDERING INFORMATION

保存环境: 干燥常温环境, 避免接触酸性和潮湿气候

版本	修改者	修改名	修改日期

未注公差		材质 MATERIAL	单位 UNIT	第三角投影	比例 SCALE	日期 DATE	品名	USB侧插外壳
X	±0.1	硬度 HRC	mm		1 : 1 (A4)	09/07/20	PRODUCT NAME	
X.X	±0.05		APPROVAL BY	CHECKED BY	DESIGNED BY	DRAWING	REV	图号
X.XX	±0.005		核准	审核	设计	绘图	版次	T10-2F198-90CP-J-W-01
X.XXX	±0.002						A	CMTDDZ 东莞市田都科技有限公司 Dongguan Tiandu Technology Co., Ltd.

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